

## Date & Venue

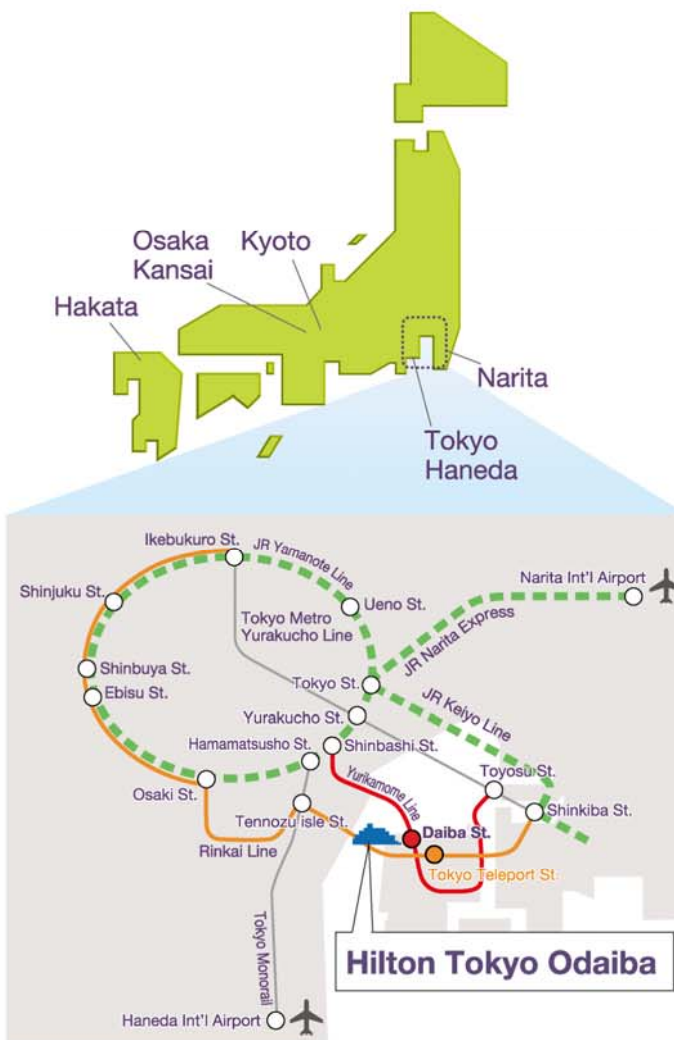
**Date:** October 24-27, 2016

**Venue:** \*Hilton Tokyo Odaiba (Hotel Nikko Tokyo)  
1-9-1 Daiba, Minato-ku, Tokyo 135-8625, Japan  
\*Hotel Nikko Tokyo is to re-brand as Hilton Tokyo Odaiba from Oct. 1, 2015.

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## Access to Venue



**Venue:**  
Hilton Tokyo Odaiba (Hotel Nikko Tokyo)  
1-9-1 Daiba, Minato-ku, Tokyo 135-8625  
Tel: +81-3-5500-5500 / Fax: +81-3-5500-5525

## Contact

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# RadTech Asia 2016

Innovation Challenges with  
New UV/EB Technologies



October  
24-27, 2016  
Tokyo,  
Japan

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Sponsored by  
RadTech Japan

<http://radtech-asia.org/radtechasia2016.html>



## RadTech Asia 2016 Invitation

RadTech Japan will sponsor RadTech Asia 2016 on October 24 to 27, 2016 at Hilton Tokyo Odaiba. The theme of this conference is "Innovation Challenges with New UV/EB Technologies".

RadTech Japan has diligently pursued the development of UV/EB technology and progress and with international collaboration with like-minded global entities.

The global RadTech organization existed in North America, China, Europe, and Japan are individual associations that operate independently, each of which has and organizes their regional "RadTech" conference and other events. RadTech Asia is a Pan-Asia event involving the RadTech organizations in China, Korea, Malaysia, and Japan. It was hosted by RadTech Japan in 2011.

Many manufacturing process and technologies initially developed in Japan have subsequently been adopted by neighboring Asian countries and this is particularly true in the field of information technology. To continue its economic growth, it is clear that, Japan must continue to innovate it if it is to survive in today's highly competitive global market place.

UV/EB technologies offers the potential to enable innovation in diverse array of industrial, graphic arrest witnessed by the expanding use of UV in the production of displays, touch panels, memory media, automotive components, and electronics devices. Academic institutions and industrial R&D laboratories continue to develop new chemistries, with innovative polymer network that provide performance characteristics that were previously viewed as unattainable.

RadTech Asia 2016 will be an event at which one will be able to learn about and understand in more detail, the most recent innovations primary in Asia, but also from around the world.

As the cycle time for innovation becomes ever more compact participation in such an event is an imperative for those involved in UV/EB technology and also for those industrialists who seek better and more environmentally friendly ways to produce their products of today and those of tomorrow.

Sincerely yours,



Teruo Orikasa  
President of RadTech Japan and  
Chair of the Organizing Committee



## Keynote Speaker

Prof. Amano Hiroshi  
Nagoya University  
(2014 Nobel Laureate in Physics)  
Date: Oct. 25 (Tue) PM (Tentative)



## Main Topics (Tentative)

### Special Sessions:

- S-1 LED related technology
- S-2 3D printing technology
- S-3 Printed electronics
- S-4 Lithography and Nanoimprint

### General Sessions:

- G-1 Radiation and Photochemistry
- G-2 Advanced materials and Applications
- G-3 Radcure equipment, Testing, and Measurement
- G-4 Functional coatings
- G-5 Others (Formulations, Sustainable application, etc)

## Important Dates

**Abstract Submission Deadline: Spring, 2016**

**Early Bird Registration Deadline: Summer, 2016**

## Abstract Submissions

Participants wishing to make a presentation on the results of their recent research are cordially invited to submit a paper according to the instructions available at our website on due course. Please submit through designated on-line system. No fax and e-mail submission will be accepted. Accepted papers will be presented in either oral or poster sessions.

## Exhibition Prospectus

### ►Outline

RadTech Asia 2016 (Holding simultaneous with an international conference)  
October 24-27, 2016

Venue: Hilton Tokyo Odaiba (Hotel Nikko Tokyo)

Organized by: RadTech Asia 2016 Organizing Committee

Sponsored by: RadTech Japan

### ►Exhibition fee and Conditions

- Type A - (Max: 43 booths)

Location: Room "Orion" 1F

Booth fee: 1 booth 250,000JPY  
2 booths or more 200,000JPY / per booth

\*Height limitation: 2.4-meter

Size: Width 1.98-meter x Depth 1.98-meter, Height 2.4-meter

- Type B - (Max: 5 booths)

Location: Foyer 1F

Booth fee: 1 booth 100,000JPY

\*The exhibitor can't apply more than 2 booths.

Size: Width 1.98-meter x Depth 0.45-meter, Height 2.4-meter

### ►Privileges for exhibitors

Each exhibitor is provided with

1. One free ticket for the Buffet Dinner on Oct 25, 2016  
(Only for a type A exhibitor)
2. One free Conference Proceedings for each company

### ►Applications

After September 1, 2015, simply complete Application Form and submit it to the Secretariat by Fax or E-mail.

\*Application form will be available on our website around July, 2015.

**Deadline for exhibition application: June 30, 2016**

**For Type-A Booth**, booths location can be selected by each exhibitor on a first-come first-served basis.

Please make sure to fill in up to the second choice.

The confirmation e-mail will be sent after the application is accepted by the organizer.

For more information, please visit our website.  
<http://www.radtech-asia.org/radtechasia2016.html>

\*The detailed prospectus will be available around July, 2015